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# United States Patent [19]

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## [54] MATERIAL-SAVING RESIST SPINNER AND PROCESS

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### Related U.S. Application Data

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**427/299; 427/377; 427/385.5**

[58] Field of Search ..... **427/600, 240, 377, 299,**  
**427/385.5**

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### [57] ABSTRACT

Spin coating of resist on a semiconductor wafer is done in a controlled chamber, starting with introducing a resist solvent vapor into the chamber from a nozzle or an adjacent chamber, applying the resist by spraying a very thin layer of the resist material and then removing solvent from the chamber. The result is a saving in resist material and enhanced coating uniformity.

9 Claims, 3 Drawing Sheets

